

N-TEM52

Non-Silicone Thermal Conductive RF Absorber Pad

LiPOLY N-TEM52 is a thermally conductive absorber based upon soft magnetic materials dispersed in a non-silicone resin. It has a thermal conductivity of 2.0 W/m*K and dissipates electromagnetic radia- tion rapidly to mitigate against EMI issues.

FEATURES

- / Thermal conductivity: 2.0 W/m*K
- / Excellent absorption characteristics
- / Naturally tacky
- / Reworkable

TYPICAL APPLICATION

- / IC, CPU, MOS, LED, M/B, Heat sink / LCD-TV, Notebook PC, PC,
- Telecom device, Wireless hub / DDR II module, DVD applications,
- Hand-set applications
- / 5G base station & infrastructure
- / EV electric vehicle

SPECIFICATIONS

- / Sheet form
- / Die-cut parts

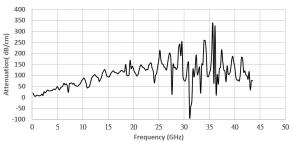
FREQUENCY APPLICATION

2.4 GHz Wi-Fi Router , Bluetooth
3.5 GHz 5G Mobile Networks
5.0 GHz Wi-Fi Router
6.0 GHz Wi-Fi Router
12~18 GHz Low Earth Orbit (LEO) System
28 GHz 5G Mobile Networks
39 GHz 5G Mobile Networks

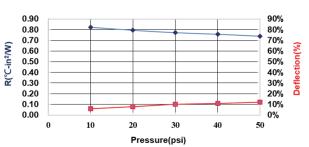
TYPICAL PROPERTIES

	PROPERTY	N-TEM52	TEST METHOD	UNIT
	Color	Dark Gray	Visual	-
-	Surface tack 2-side/1-side	2	-	-
-	Thickness	Customized	ASTM D374	mm
-	Density	4.4	ASTM D792	g/cm³
-	Hardness	60	ASTM D2240	Shore OO
-	TML	<0.8	By LiPOLY	%
-	Application temperature	-60~130	-	°C
5	ROHS & REACH	Compliant	-	-
	COMPRESSION@1.0mm			
	Deflection @10 psi	6	ASTM D5470 modify	%
-	Deflection @20 psi	8	ASTM D5470 modify	%
-	Deflection @30 psi	10	ASTM D5470 modify	%
-	Deflection @40 psi	11	ASTM D5470 modify	%
-	Deflection @50 psi	12	ASTM D5470 modify	%
k	EMI Attenuation @1.0mm			
	EMI attenuation@ 2.4 GHz	26	ASTM D4935 modify	dB/cm
-	EMI attenuation@ 3.5 GHz	30	ASTM D4935 modify	dB/cm
;, ⁻	EMI attenuation@ 5.0 GHz	49	ASTM D4935 modify	dB/cm
-	EMI attenuation@ 6.0 GHz	50	ASTM D4935 modify	dB/cm
-	EMI attenuation@ 12 GHz	96	ASTM D4935 modify	dB/cm
-	EMI attenuation@ 18 GHz	116	ASTM D4935 modify	dB/cm
-	EMI attenuation@ 28 GHz	135	ASTM D4935 modify	dB/cm
	EMI attenuation@ 39 GHz	113	ASTM D4935 modify	dB/cm
	ELECTRICAL			'
	Surface resistivity	>1011	ASTM D257	Ohm
l	Volume resistivity	>1010	ASTM D257	Ohm-m
	THERMAL			
	Thermal Conductivity	2.0	ASTM D5470	W/m*K
-	Thermal impedance@10 psi	0.823	ASTM D5470	°C-in²/ W
-	Thermal impedance@20 psi	0.794	ASTM D5470	°C-in²/ W
-	Thermal impedance@30 psi	0.771	ASTM D5470	°C-in²/ W
-	Thermal impedance@40 psi	0.756	ASTM D5470	°C-in²/ W
-	Thermal impedance@50 psi	0.737	ASTM D5470	°C-in²/ W
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Attenuation



Thermal Resistance vs. Pressure vs. Deflection



Note: All specifications provided by LiPOLY are subject to change without notice. The test methods used by LiPOLY are based on the TIM Tester method and ASTM D5470 test method. These test methods are used as the definition standards for LiPOLY. Property values provided in this document are not for product specifications or guaranteed. This document does not guarantee the performance and quality required for the purchaser's specific ourpose. The protest methods are used as the definition standards for LiPOLY. Stafety before using the material. We strongly recommend the purchaser pretest the product and verify the performance of the product tare's specific conditions. Liability and use of the product are the responsibility of the end user. LiPOLY makes no warranty as to the suitability, merchantability, or non-infringement of any LiPOLY material or product for any specific or general uses. LiPOLY shall not be liable for incidental orconsequential damages of any kind. All LiPOLY products are sold in accordance with the LiPOLY Terms and Conditions in effect at the time of purchase and a copy of which will be furnished upon request. All ripots reserved, including LiPOLY trademarks or registered trademarks of LiPOLY or its affiliates. Statements concerning possible or suggested uses made herein shall not be relied upon or be constructed as a guaranty of patent infringement. Copyright 2023 LiPOLY.